

ABSTRACT

A method for manufacturing an EMI-shielding assembly having a substrate comprises the steps of: (a) providing oxygen plasma to clean the substrate; (b) ion plating the cleaned substrate with an adhesion layer comprising nickel; (c) ion plating the plated substrate with a metal shielding layer comprising copper; and (d) ion plating the plated substrate with a corrosion-resistant layer comprising stainless steel. The EMI-shielding assembly made by this method has a very firm adhesion between the substrate and the metal layers. Moreover, the EMI-shielding assembly has superb characteristics for shielding EMI since the substrate has a more uniform shielding layer. In addition, this method is very suitable for making an EMI-shielding object which has an irregular shape.